

ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-00247

REV: E1

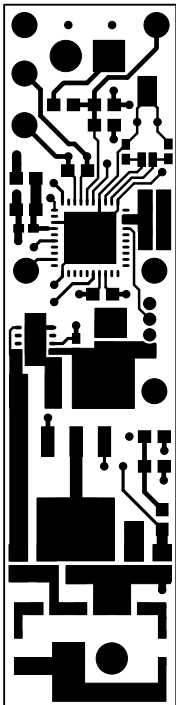
SUN REV: Not In VersionControl

LAYER NAME = Top Solder

PLOT NAME = TIDA-00247\_E1.GTS

GENERATED : 10/28/2014 4:12:06 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-00247

REV: E1

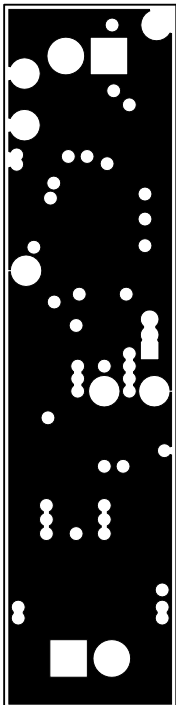
SUN REV: Not In VersionControl

LAYER NAME = Top Layer

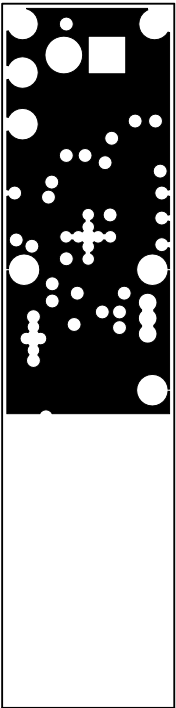
PLOT NAME = TIDA-00247\_E1.GTL

GENERATED : 10/28/2014 4:12:05 PM

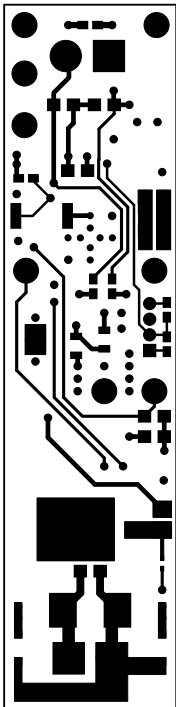
TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00247	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer2_GND Plane			
PLOT NAME = TIDA-00247_E1.G1	GENERATED : 10/28/2014 4:12:05 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00247	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer3_UCC Plane			
PLOT NAME = TIDA-00247_E1.G2	GENERATED : 10/28/2014 4:12:05 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-00247

REV: E1

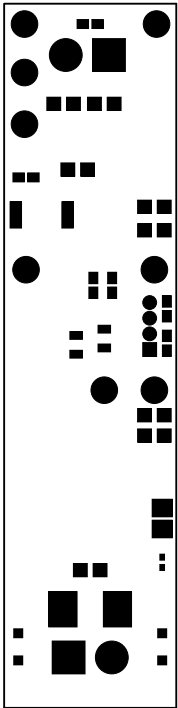
SUN REV: Not In VersionControl

LAYER NAME = Bottom Layer

PLOT NAME = TIDA-00247\_E1.GBL

GENERATED : 10/28/2014 4:12:05 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-00247

REV: E1

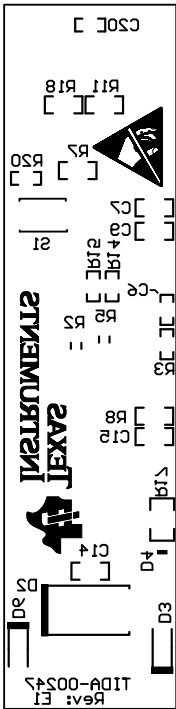
SUN REV: Not In VersionControl

LAYER NAME = Bottom Solder

PLOT NAME = TIDA-00247\_E1.GBS

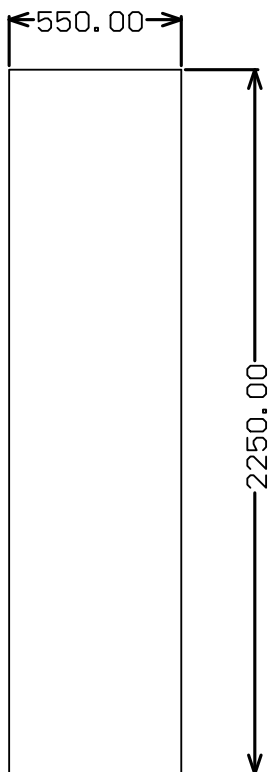
GENERATED : 10/28/2014 4:12:06 PM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00247	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = TIDA-00247_E1.GBO	GENERATED : 10/28/2014 4:12:06 PM	TEXAS INSTRUMENTS	





ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00247	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Board Outline			
PLOT NAME = TIDA-00247_E1.GM1	GENERATED : 10/28/2014 4:16:56 PM	TEXAS INSTRUMENTS	

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